# 800 mA, Adjustable Output, **Low Dropout Voltage** Regulator

The MC33269/NCV33269 series are low dropout, medium current, fixed and adjustable, positive voltage regulators specifically designed for use in low input voltage applications. These devices offer the circuit designer an economical solution for precision voltage regulation, while keeping power losses to a minimum.

The regulator consists of a 1.0 V dropout composite PNP-NPN pass transistor, current limiting, and thermal shutdown.

#### **Features**

- 3.3 V, 3.5 V, 5.0 V, 12 V and Adjustable Versions 2.85 V version available as MC34268
- Space Saving DPAK, SO-8 and SOT-223 Power Packages
- 1.0 V Dropout
- Output Current in Excess of 800 mA
- Thermal Protection
- Short Circuit Protection
- Output Trimmed to 1.0% Tolerance
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices

#### **DEVICE TYPE/NOMINAL OUTPUT VOLTAGE**

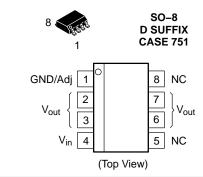
MC33269D	Adj	MC33269T-3.5	3.5 V
NCV33269D*	Adj	MC33269D-5.0	5.0 V
MC33269DT	Adj	MC33269DT-5.0	5.0 V
NCV33269DTRK*	Adj	NCV33269DT-5.0*	5.0 V
MC33269T	Adj	NCV33269DTRK-5.0*	5.0 V
MC33269D-3.3	3.3 V	MC33269T-5.0	5.0 V
MC33269DT-3.3	3.3 V	MC33269D-012	12 V
NCV33269DTRK-3.3*	3.3 V	MC33269DT-012	12 V
MC33269T-3.3	3.3 V	NCV33269DTRK-012*	12 V
MC33269ST-3.3	3.3 V	MC33269T-012	12 V

\*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.



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#### **DPAK DT SUFFIX CASE 369C**

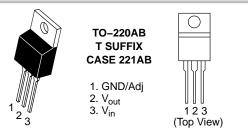
1. GND/Adj  $2.\ V_{out}$ 3. V<sub>in</sub>

SOT-223 ST SUFFIX **CASE 318E** 





Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.



Heatsink surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 8 of this data sheet.

#### **MAXIMUM RATINGS**

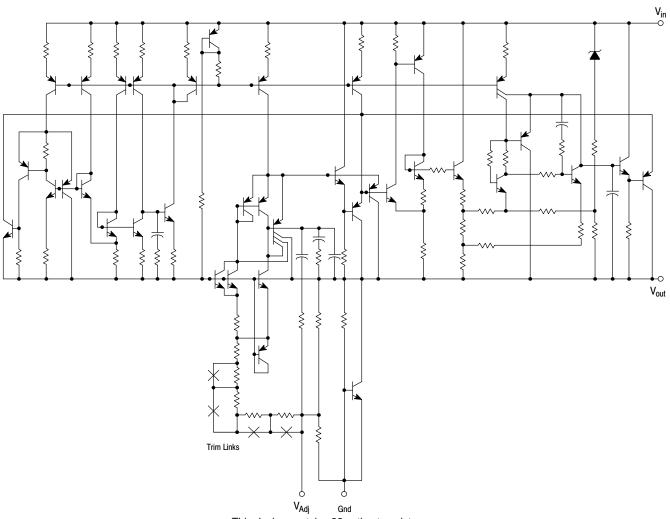
	Rating	Symbol	Value	Unit
Power Supply Input Voltage		V <sub>in</sub>	20	V
Power Dissipation				
Case 369C (DPAK)	T <sub>A</sub> = 25°C Thermal Resistance, Junction-to-Ambient Thermal Resistance, Junction-to-Case	P <sub>D</sub> θ <sub>JA</sub> θ <sub>JC</sub>	Internally Limited 92 6.0	°C/W
Case 751 (SO-8)	T <sub>A</sub> = 25°C Thermal Resistance, Junction-to-Ambient Thermal Resistance, Junction-to-Case	P <sub>D</sub> θ <sub>JA</sub> θ <sub>JC</sub>	Internally Limited 160 25	°C/W
Case 221A (TO-220)	T <sub>A</sub> = 25°C Thermal Resistance, Junction-to-Ambient Thermal Resistance, Junction-to-Case	P <sub>D</sub> θJA θJC	Internally Limited 65 5.0	°C/W
Case 318E (SOT-223)	T <sub>A</sub> = 25°C Thermal Resistance, Junction-to-Ambient Thermal Resistance, Junction-to-Case	P <sub>D</sub> θ <sub>JA</sub> θ <sub>JC</sub>	Internally Limited 156 15	°C/W
Operating Die Junction Tem	perature Range	TJ	-40 to +150	°C
Operating Ambient Temperature Range MC33269 NCV33269		T <sub>A</sub>	-40 to +125 -40 to +125	°C
Storage Temperature		T <sub>stg</sub>	-55 to +150	°C
Electrostatic Discharge Sens	sitivity (ESD) Human Body Model (HBM) Machine Model (MM)	ESD	4000 400	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## **ELECTRICAL CHARACTERISTICS** ( $C_O$ = 10 $\mu$ F, $T_A$ = 25°C, for min/max values $T_A$ = -40°C to +125°C, unless otherwise noted.)

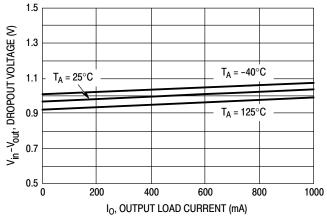
Characteristic	Symbol	Min	Тур	Max	Unit
Output Voltage ( $I_{out}$ = 10 mA, $T_A$ = 25°C) 3.3 Suffix ( $V_{CC}$ = 5.3 V 3.5 Suffix ( $V_{CC}$ = 5.5 V 5.0 Suffix ( $V_{CC}$ = 7.0 V 12 Suffix ( $V_{CC}$ = 14 V		3.27 3.465 4.95 11.88	3.3 3.5 5.0 12	3.33 3.535 5.05 12.12	V
Output Voltage (Line, Load and Temperature) (Note 1) $ (1.25\ V \le V_{in} - V_{out} \le 15\ V,\ I_{out} = 500\ mA) $ $ (1.35\ V \le V_{in} - V_{out} \le 10\ V,\ I_{out} = 800\ mA) $ $ 3.3\ Suffix $ $ 3.5\ Suffix $ $ 5.0\ Suffix $ $ 12\ Suffix $		3.23 3.43 4.90 11.76	3.3 3.5 5.0 12	3.37 3.57 5.10 12.24	V
Reference Voltage for Adjustable Voltage (I <sub>out</sub> = 10 mA, V <sub>in</sub> - V <sub>out</sub> = 2.0 V, T <sub>A</sub> = 25°C)	V <sub>ref</sub>	1.235	1.25	1.265	V
Reference Voltage (Line, Load and Temperature) (Note 1) for Adjustable Voltage (1.25 V $\leq$ V <sub>in</sub> $-$ V <sub>out</sub> $\leq$ 15 V, I <sub>out</sub> $=$ 500 mA) (1.35 V $\leq$ V <sub>in</sub> $-$ V <sub>out</sub> $\leq$ 10 V, I <sub>out</sub> $=$ 800 mA)		1.225	1.25	1.275	V
Line Regulation $(I_{out} = 10 \text{ mA}, V_{in} = [V_{out} + 1.5 \text{ V}] \text{ to } V_{in} = 20 \text{ V}, T_A = 25^{\circ}\text{C}$	Reg <sub>line</sub>	_	_	0.3	%
Load Regulation $(V_{in} = V_{out} + 3.0 \text{ V}, I_{out} = 10 \text{ mA to } 800 \text{ mA}, T_A = 25^{\circ}\text{C}$	Reg <sub>load</sub>	_	_	0.5	%
Dropout Voltage	III Out	-	1.0 1.1	1.25 1.35	V
Ripple Rejection (10 $V_{pp}$ , 120 Hz Sinewave; $I_{out}$ = 500 mA)		55	_	-	dB
Current Limit $(V_{in} - V_{out} = 10 \text{ V})$	I <sub>Limit</sub>	800	-	-	mA
Quiescent Current (Fixed Output) $ (1.5 \text{ V} \le \text{V}_{\text{out}} \le 3.5 \text{ V} \\  (5 \text{ V} \le \text{V}_{\text{out}} \le 12 \text{ V} ) $			5.5 -	8.0 20	mA
Minimum Required Load Current Fixed Output Voltage Adjustable Voltage		- 8.0	- -	0 –	mA
Adjustment Pin Current	I <sub>Adi</sub>			120	μΑ

<sup>1.</sup> The MC33269–12, V<sub>in</sub> – V<sub>out</sub> is limited to 8.0 V maximum, because of the 20 V maximum rating applied to V<sub>in</sub>.



This device contains 38 active transistors.

Figure 1. Internal Schematic



NOTPUT OVO OUTPUT OVO OUTPUT OUTPUT

Figure 2. Dropout Voltage versus
Output Load Current

Figure 3. Transient Load Regulation

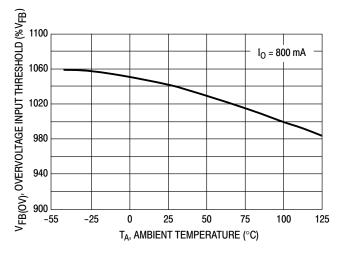


Figure 4. Dropout Voltage versus Temperature

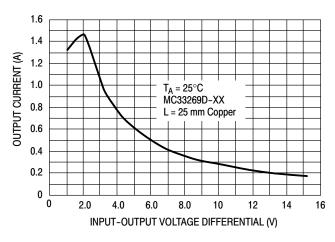


Figure 5. MC33269-XX Output DC Current versus Input-Output Differential Voltage

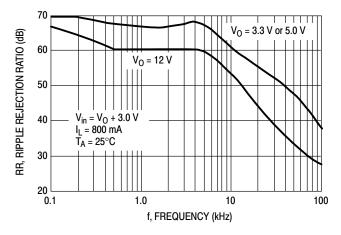


Figure 6. MC33269 Ripple Rejection versus Frequency

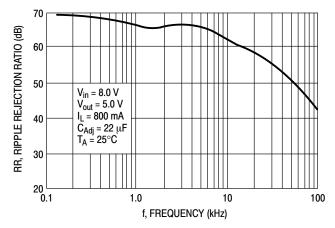


Figure 7. MC33269–ADJ Ripple Rejection versus Frequency

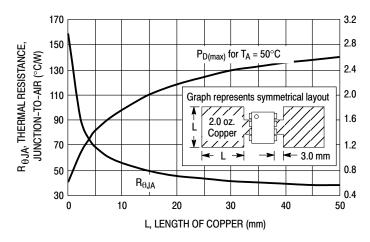


Figure 8. SOP-8 Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

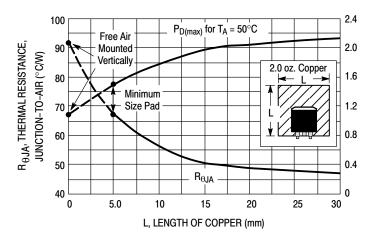


Figure 9. DPAK Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

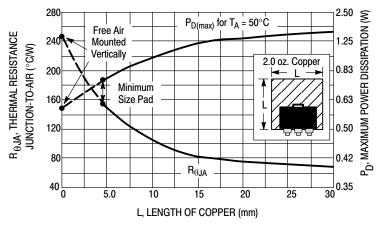


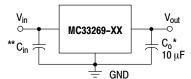
Figure 10. SOT–223 Thermal Resistance and Maximum Power Dissipation versus P.C.B. Copper Length

#### APPLICATIONS INFORMATION

Figures 11 through 15 are typical application circuits. The output current capability of the regulator is in excess of 800 mA, with a typical dropout voltage of less than 1.0 V. Internal protective features include current and thermal limiting.

\* The MC33269 requires an external output capacitor for stability. The capacitor should be at least 10  $\mu F$  with an equivalent series resistance (ESR) of less than 10  $\Omega$  but greater than 0.2  $\Omega$  over the anticipated operating temperature range. With economical electrolytic capacitors, cold temperature operation can pose a problem. As temperature decreases, the capacitance also decreases and the ESR increases, which could cause the circuit to oscillate. Also capacitance and ESR of a solid tantalum capacitor is more stable over temperature. The use of a low ESR ceramic capacitor placed within close proximity to the output of the device could cause instability.

\*\* An input bypass capacitor is recommended to improve transient response or if the regulator is connected to the



An input capacitor is not necessary for stability, however it will improve the overall performance.

Figure 11. Typical Fixed Output Application

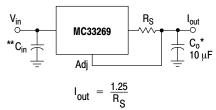
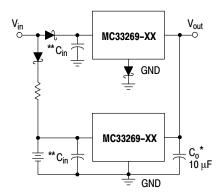


Figure 13. Current Regulator

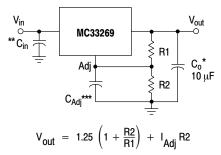


The Schottky diode in series with the ground leg of the upper regulator shifts its output voltage higher by the forward voltage drop of the diode. This will cause the lower device to remain off until the input voltage is removed.

Figure 14. Battery Backed-Up Power Supply

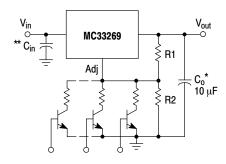
supply input filter with long wire lengths. This will reduce the circuit's sensitivity to the input line impedance at high frequencies. A 0.33  $\mu F$  or larger tantalum, mylar, ceramic, or other capacitor having low internal impedance at high frequencies should be chosen. The bypass capacitor should be mounted with shortest possible lead or track length directly across the regulator's input terminals. **Applications should be tested over all operating conditions to insure stability.** 

Internal thermal limiting circuitry is provided to protect the integrated circuit in the event that the maximum junction temperature is exceeded. When activated, typically at 170°C, the output is disabled. There is no hysteresis built into the thermal limiting circuit. As a result, if the device is overheating, the output will appear to be oscillating. This feature is provided to prevent catastrophic failures from accidental device overheating. It is not intended to be used as a substitute for proper heat–sinking.



\*\*\*C<sub>Adj</sub> is optional, however it will improve the ripple rejection. The MC34269 develops a 1.25 V reference voltage between the output and the adjust terminal. Resistor R1, operates with constant current to flow through it and resistor R2. This current should be set such that the Adjust Pin current causes negligible drop across resistor R2. The total current with minimum load should be greater than 8.0 mA.

Figure 12. Typical Adjustable Output Application



 ${\rm R}_2$  sets the maximum output voltage. Each transistor reduces the output voltage when turned on.

Figure 15. Digitally Controlled Voltage Regulator

#### **ORDERING INFORMATION**

Device	Package	Shipping Information <sup>†</sup>
MC33269DG	SO-8 (Pb-Free)	98 Units / Rail
MC33269DR2G	SO-8 (Pb-Free)	2500 Units / Tape & Reel
MC33269DTG	DPAK (Pb-Free)	75 Units / Rail
MC33269DTRKG	DPAK (Pb-Free)	2500 Units / Tape & Reel
MC33269TG	TO-220 (Pb-Free)	50 Units / Rail
MC33269D-3.3G	SO-8 (Pb-Free)	98 Units / Rail
MC33269DR2-3.3G	SO-8 (Pb-Free)	2500 Units / Tape & Reel
MC33269DT-3.3G	DPAK (Pb-Free)	75 Units / Rail
MC33269DTRK-3.3G	DPAK (Pb-Free)	2500 Units / Tape & Reel
MC33269ST-3.3T3G	SOT-223 (Pb-Free)	4000 Units / Tape & Reel
MC33269T-3.3G	TO-220 (Pb-Free)	50 Units / Rail
MC33269T-3.5G	TO-220 (Pb-Free)	50 Units / Rail
MC33269D-5.0G	SO-8 (Pb-Free)	98 Units / Rail
MC33269DR2-5.0G	SO-8 (Pb-Free)	2500 Units / Tape & Reel
MC33269DT-5.0G	DPAK (Pb-Free)	75 Units / Rail
NCV33269DT-5.0G*	DPAK (Pb-Free)	75 Units / Rail
MC33269DTRK-5.0G	DPAK (Pb-Free)	2500 Units / Tape & Reel
MC33269T-5.0G	TO-220 (Pb-Free)	50 Units / Rail
MC33269D-012G	SO-8 (Pb-Free)	98 Units / Rail
MC33269DR2-012G	SO-8 (Pb-Free)	2500 Units / Tape & Reel
MC33269DT-012G	DPAK (Pb-Free)	75 Units / Rail
MC33269DTRK-012G	DPAK (Pb-Free)	2500 Units / Tape & Reel
MC33269T-012G	TO-220 (Pb-Free)	50 Units / Rail
NCV33269DR2G*	SO-8 (Pb-Free)	2500 Units / Tape & Reel
NCV33269DTRKG*	DPAK (Pb-Free)	2500 Units / Tape & Reel
NCV33269DTRK3.3G*	DPAK (Pb-Free)	2500 Units / Tape & Reel
NCV33269DTRK5.0G*	DPAK (Pb-Free)	2500 Units / Tape & Reel
NCV33269DTRK-12G*	DPAK (Pb-Free)	2500 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

#### **MARKING DIAGRAMS**

SO-8 D SUFFIX CASE 751









DPAK DT SUFFIX CASE 369C

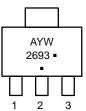




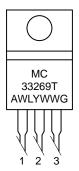


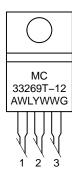


SOT-223 ST SUFFIX CASE 318E



TO-220AB T SUFFIX CASE 221A









A = Assembly Location

L, WL = Wafer Lot Y = Year

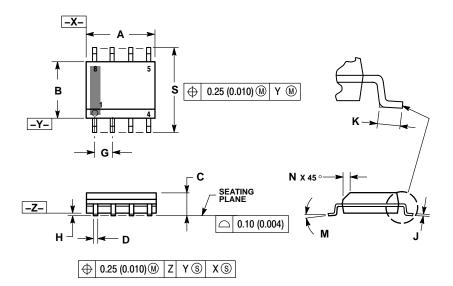
W, WW = Work Week

G = Pb-Free Package = Pb-Free Package

(Note: Microdot may be in either location)

#### PACKAGE DIMENSIONS

### SO-8 **D SUFFIX** CASE 751-07 **ISSUE AK**



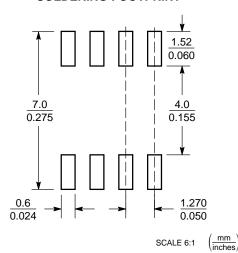
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION A AND B DO NOT INCLUDE
  MOLD PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 (0.006)
  PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL
  IN EXCESS OF THE D DIMENSION AT
  MAXIMUM MATERIAL CONDITION.
  751–01 THRU 751–06 ARE OBSOLETE. NEW
  STANDARD IS 751–07.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004 0.010		
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016 0.050		
М	0 °	8 °	0 ° 8 °		
N	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

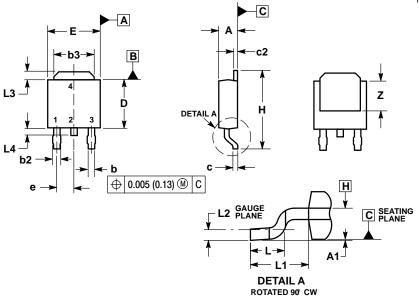
### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **PACKAGE DIMENSIONS**

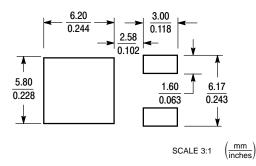
### **DPAK DT SUFFIX** CASE 369C ISSUE D



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: INCHES.
  3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE
  - 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY. 6. DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.086	0.094	2.18	2.38	
A1	0.000	0.005	0.00	0.13	
b	0.025	0.035	0.63	0.89	
b2	0.030	0.045	0.76	1.14	
b3	0.180	0.215	4.57	5.46	
С	0.018	0.024	0.46	0.61	
c2	0.018	0.024	0.46	0.61	
D	0.235	0.245	5.97	6.22	
Е	0.250	0.265	6.35	6.73	
е	0.090	BSC	2.29 BSC		
Н	0.370	0.410	9.40	10.41	
L	0.055	0.070	1.40	1.78	
L1	0.108	0.108 REF		REF	
L2	0.020 BSC		0.51	BSC	
L3	0.035	0.050	0.89	1.27	
L4		0.040		1.01	
Z	0.155		3.93		

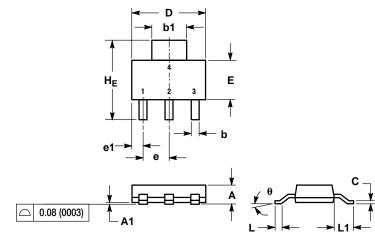
### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **PACKAGE DIMENSIONS**

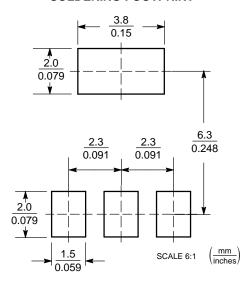
### SOT-223 **ST SUFFIX** CASE 318E-04 ISSUE N



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS		INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		I
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	_	10°	0°	-	10°

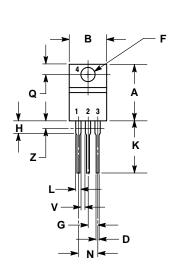
### **SOLDERING FOOTPRINT\***

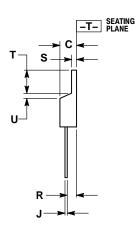


\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

### TO-220, SINGLE GAUGE **T SUFFIX** CASE 221AB ISSUE A





#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCHES.
  DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.
  PRODUCT SHIPPED PRIOR TO 2008 HAD DIMENSIONS
- S = 0.045 0.055 INCHES (1.143 1.397 MM)

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.020	0.024	0.508	0.61
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

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